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**CONFIRMATION NO. 2275** 

SERIAL NUMBER 10/24/2003	Bib Data Sheet										
Kiyoshi Ooi, Nagano-shi, JAPAN; Yasuyoshi Horikawa, Nagano-shi, JAPAN;  **CONTINUING DATA ***  **FOREIGN APPLICATIONS *** JAPAN 2002-314695 10/29/2002  IF REQUIRED, FOREIGN FILING LICENSE GRANTED *** 01/23/2004  Foreign Priority claimed yes no Met after The Moderate of		ER	10/24/2003	(	1			DOCKET NO.			
Yasuyoshi Horikawa, Nagano-shi, JAPAN;  **CONTINUING DATA***  **FOREIGN APPLICATIONS*** JAPAN 2002-314695 10/29/2002  IF REQUIRED, FOREIGN FILING LICENSE GRANTED  **01/23/2004  Foreign Priority claimed	APPLICANTS										
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IF REQUIRED, FOREIGN FILING LICENSE GRANTED  *** 01/23/2004  Foreign Priority claimed	Yasuyoshi Horikawa, Nagano-shi, JAPAN;										
IF REQUIRED, FOREIGN FILING LICENSE GRANTED  *** 01/23/2004  Foreign Priority claimed  35 USC 119 (a-d) conditions	** CONTINUING DATA **********************************										
** 01/23/2004  Foreign Priority claimed 35 USC 119 (a-d) conditions 2 yes 0 no 0 Met after Werified and Acknowledged Examiner's Signature Initials DRAWING CLAIMS 20 3  ADDRESS 26530 LADAS & PARRY LLP 224 SOUTH MICHIGAN AVENUE SUITE 1600 CHICAGO , IL 60604  TITLE Substrate for carrying a semiconductor chip and a manufacturing method thereof  FILING FEE FEES: Authority has been given in Paper No to charge/credit DEPOSIT ACCOUNT No for following: 1.18 Fees (Issue)	JAPAN 2002-314695 10/29/2002										
35 USC 119 (a-d) conditions											
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